Advanced Small Signal MOSFET 2N7000BU/2N7000TA

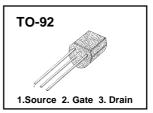
FEATURES

- Fast Switching Times
- Improved Inductive Ruggedness
- Lower Input Capacitance
- Extended Safe Operating Area
- Improved High Temperature Reliability

 $BV_{DSS} = 60 V$

 $R_{DS(on)} = 5.0 \Omega$

 $I_D = 200 \text{ mA}$



Absolute Maximum Ratings

Symbol	Characteristic	Value	Units	
V_{DSS}	Drain-to-Source Voltage	60	V	
,	Continuous Drain Current (T _C =25°C)	200	mA	
I _D	Continuous Drain Current (T _C =100℃)	110] IIIA	
I _{DM}	Drain Current-Pulsed ① 1000		mA	
V_{GS}	Gate-to-Source Voltage	±30	V	
_	Total Power Dissipation (T _C =25°C)	400	mW	
P_{D}	Linear Derating Factor	3.2	mW/℃	
	Operating Junction and	55 / 450	°C	
T_J , T_STG	Storage Temperature Range	- 55 to +150		
_	Maximum Lead Temp. for Soldering	000		
T_L	Purposes, 1/8? from case for 5-seconds	300		

Thermal Resistance

Symbol	Characteristic	Тур.	Max.	Units
$R_{\scriptscriptstyle{\ThetaJA}}$	Junction-to-Ambient		312.5	сw



2N7000BU/2N7000TA

Electrical Characteristics (T_C =25 $^{\circ}$ C unless otherwise specified)

Symbol	Characteristic	Min.	Тур.	Max.	Units	Test Condition	
BV _{DSS}	Drain-Source Breakdown Voltage	60	-		V	V _{GS} =0V,I _D =250μA	
$V_{GS(th)}$	Cata Threshold Valtage			3.9	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$	
V GS(th)	Gate Threshold Voltage	0.4		2.2	V	$V_{DS} = V_{GS}, I_{D} = 1 \text{mA}$	
	Gate-Source Leakage, Forward			100	nA	V _{GS} =15V	
I _{GSS}	Gate-Source Leakage, Reverse			-100	IIA	V _{GS} =-15V	
	Drain-to-Source Leakage Current			1	μA	V _{DS} =60V	
I _{DSS}				1000		V _{DS} =45V,T _C =125°C	
_	Static Drain-Source					V 40VI 0.5A	
R _{DS(on)}	On-State Resistance ②		5.0	5.0	Ω	V _{GS} =10V,I _D =0.5A	
g _{fs}	Forward Transconductance ②	0.1	0.3		S	$V_{DS} = 15V, I_{D} = 0.5A$	
C _{iss}	Input Capacitance		30			V 0V/V 25V	
C _{oss}	Output Capacitance		12		рF	$V_{GS}=0V, V_{DS}=25V,$ f=1MHz	
C _{rss}	Reverse Transfer Capacitance		3.0			I = IIVI⊓Z	
t _{d(on)}	Turn-On Delay Time			10			
t _r	Rise Time			10		V_{DD} =30V, I_{D} =0.5A,	
t _{d(off)}	Turn-Off Delay Time			10	ns	$R_G=15\Omega$ ②③	
t _f	Fall Time			10			

Notes

- ① Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- ② Pulse Test : Pulse Width = 250µs, Duty Cycle ≤ 2%
- 3 Essentially Independent of Operating Temperature



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